

HSEC8-149-01-L-DV-A



**HSEC8-DV SERIES**

**(0.80 mm) .0315"**

# VERTICAL EDGE RATE® CARD SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HSEC8-DV](http://www.samtec.com?HSEC8-DV)

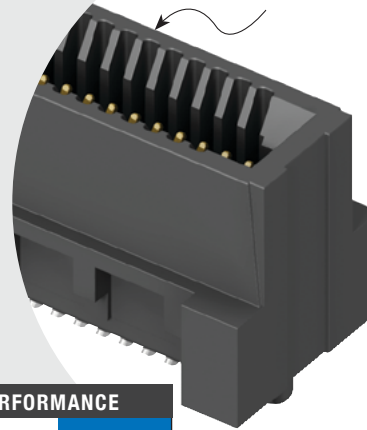
**Insulator Material:**  
Black Liquid Crystal Polymer  
**Contact:**  
BeCu  
**Plating:**  
Au or Sn over  
50 μ" (1.27 μm) Ni  
**Current Rating:**  
2.8 A per pin  
(2 adjacent pins powered)  
**Operating Temp:**  
-55 °C to +125 °C  
**RoHS Compliant:**  
Yes

**Card Mates:**  
(1.60 mm) .062" card,  
(2.36 mm) .093" card,  
HSC8

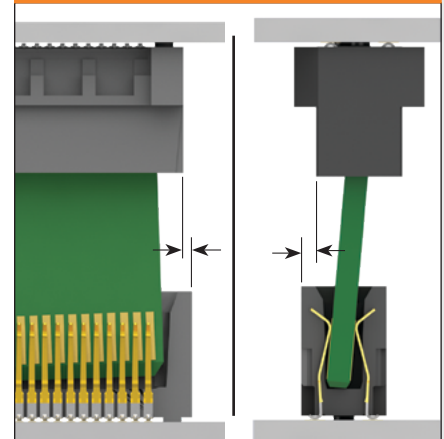
**Cable Mates:**  
ECDP



Mates with (1.60 mm) .062"  
or (2.36 mm) .093" cards



## MISALIGNMENT MITIGATION



Custom designs compensate for misalignment. Contact Samtec.

## PROCESSING

**Lead-Free Solderable:**  
Yes  
**SMT Lead Coplanarity:**  
(0.10 mm) .004" max (10-60)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## HIGH-SPEED CHANNEL PERFORMANCE

HSEC8-DV

Rating based on Samtec reference channel.  
For full SI performance data visit [Samtec.com](http://Samtec.com)  
or contact [SIG@samtec.com](mailto:SIG@samtec.com)

**28**  
Gbps

## HSEC8 - 1 POSITIONS PER ROW - CARD THICKNESS - PLATING OPTION - DV - A - OTHER OPTION

**09, 10, 13, 20, 25, 30, 37, 40, 49, 50, 60, 70, 80, 100**  
(13, 25, 49 only available with -L or -L2 option;  
09 only available with -L2 option;  
37 only available with -L option)

**-01**  
= (1.60 mm) .062" thick card  
**-03**  
= (2.36 mm) .093" thick card

**-L**  
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail  
**-S**  
= 30 μ" (0.76 μm) Gold on contact, Matte Tin on tail

**-K**  
= (7.01 mm) .276" DIA Polyimide Film Pick & Place Pad (with -01 card)  
= (6.25 mm) .246" DIA Polyimide Film Pick & Place Pad (with -03 card)

**-BL**  
= Board Locks (-01 card only) (Weld tab standard)

**-L**  
= Latching Option (-01 card only) (13, 25, 37, 49 only) (Weld tab standard)

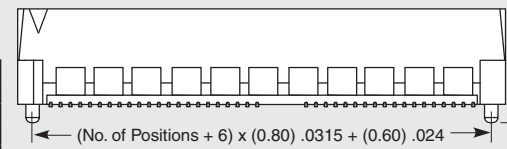
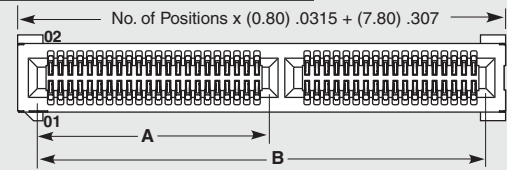
**-L2**  
= ECDP Latching (-01 card only) (09, 13, 25, 49 only) (For use with ECDP) (Weld tab standard)

**-WT**  
= Weld tab

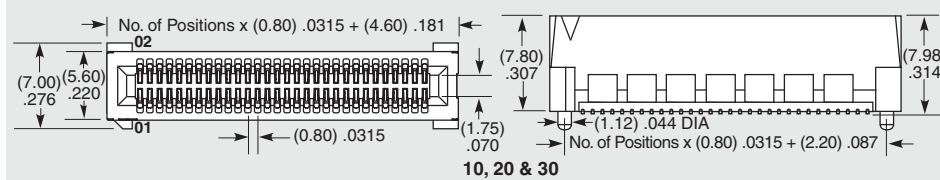
**-TR**  
= Tape & Reel (09 - 70 only)

POSITIONS PER ROW	A	B
09*†	(4.50) .177	(11.80) .465
13*†	(6.10) .240	(15.00) .591
25*†	(6.10) .240	(24.60) .969
37†	(18.10) .713	(34.20) 1.346
40	(18.90) .744	(36.60) 1.441
49*†	(22.90) .902	(43.80) 1.724
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071
70†	(26.90) 1.059	(60.60) 2.386
80†	(26.90) 1.059	(68.60) 2.701
100†	(26.90) 1.059	(84.60) 3.331

Positions where no dimensions are given do not have keying feature.  
\* Mates with ECDP Series.  
† Available with -01 Card Only.



09, 13, 25, 37, 100



CABLE CONNECTOR	HSEC8-109-L2
ECDP-04	HSEC8-109-L2
ECDP-08	HSEC8-113-L2
ECDP-16	HSEC8-125-L2
ECDP-32	HSEC8-149-L2

### Notes:

While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications. Contact Samtec for further information.

Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.